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Applications of Industrial Internet of Things (IIoT) Platforms

Guest Editor:

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Deadline for manuscript submissions: **20 October 2024**

Message from the Guest Editor

This Special Issue will promote state-of-the-art research, covering all aspects of IIoT applications, but are not limited to, the following:

- artificial intelligence
- distributed systems
- Industrial IoT
- Industry 4.0
- Industry 5.0
- cyber-physical systems
- human-robot interaction
- industrial maintenance systems
- industrial automation
- deep learning industrial applications
- decision support systems
- digital twins
- VR
- AR industry appliances
- industrial robotics
- haptic systems and teleoperations

Specialsue



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Editor-in-Chief

Message from the Editor-in-Chief

Prof. Dr. Giulio Nicola Cerullo Dipartimento di Fisica, Politecnico di Milano, Piazza L. da Vinci 32, 20133 Milano, Italy As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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